

1 ABSTRACT OF THE DISCLOSURE

2 In one aspect, the invention includes a method of encapsulating
3 a semiconductor device, comprising: a) providing a semiconductor device;
4 b) providing a dispensing apparatus having a plurality of dispensing
5 orifices proximate the semiconductor device; and c) dispensing a liquid
6 encapsulating material through the plurality of orifices and over the
7 semiconductor device. In another aspect, the invention includes a
8 method of forming an electronic package, comprising: a) providing a
9 circuit board having a circuit pattern; b) joining a plurality of
10 semiconductor devices to the circuit board in electrical connection with
11 the circuit pattern; c) providing a dispensing apparatus having a plurality
12 of dispensing orifices proximate the semiconductor devices; d)
13 simultaneously dispensing liquid encapsulating material through at least
14 two of the plurality of orifices and over at least two of the
15 semiconductor devices; and e) curing the liquid encapsulating material.

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